

- 特征 -

1. 新机种

- Achieved the best performance by the renewal optics for advanced inspection.

2. 生产效率为行业最高水平

- Implement the HIGHEST throughput to further increase productivity.

3. 尺寸紧凑，便于操作

- Compact size with simple structure and improved accessibility/ maintenance.



可支持新一代IC封装电路板3D Bump

高度及直径的同步检测等

(u-Bump, 压平/未压平Bump, CAW等)

Capable of implementing next-generation IC Substrate 3D Bump inspection.
Apply for Height & Vision inspection simultaneously (u-Bump, Round/Flattened, Warpage)

高速度・高精度检测

- Higher Throughput & Accuracy

优化用户界面

- Optimized Interface, Increased Usability

Key Specifications	Optical Sensor RSH-12i
2D sensor method	2D CMOS Area Camera & LED Lighting (dark & bright field)
3D sensor method	3D Laser Triangulation
Typical Bump Diameter Range (μm) ※1	35 to 250μm
Typical Bump Height Range (μm)	0 to 200μm
Typical Bump pitch (μm)	< Bump Diameter × 2
Typical Device size (width) x (Depth) (mm)	7mm (W) x 7mm (D) - 120mm (W) x 120mm (D)
Typical Substrate thickness Range (mm)	0.2mm - 4mm
2D resolution(X,Y) (μm)	2.4μm
3D resolution(X,Y) (μm)	X: 5μm Y:Programmable 1-50μm
3D resolution(Z) (μm) on flat surface	0.11μm
FOV (mm)	>12mm
2D accuracy mean bias (μm) ※2	±1.9μm
3D accuracy mean bias (μm) ※2	±1.3μm
Repeatability bump height (μm) ※2	3σ mean ≤ 1.5μm
Repeatability bump diameter (μm) ※2	3σ mean ≤ 1.5μm
Repeatability bump coplanarity (μm) ※2	3σ mean ≤ 1.5μm
Machine size/weight	Size: 1860mm (W) x 2400mm (D) x 2050mm (H) ※Protrusion part is not included. Weight: approx. 3000kg

※1: min. diameter range: 25μm supported for bump with flattened no damage surface.

※2: Specifications are subject to change. Performance specifications on golden units. Exact specifications to be tested with customer samples.

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NIDEC ADVANCE TECHNOLOGY CORPORATION

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More details...